

SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

- 1

SN54LVTH16500, SN74LVTH16500

3.3-V ABT 18-BIT UNIVERSAL BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

description/ordering information (continued)

Data flow in each direction is controlled by output-enable ($\overline{\text{OEAB}}$ and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock ($\overline{\text{CLKAB}}$ and $\overline{\text{CLKBA}}$) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{\text{CLKAB}}$ is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of $\overline{\text{CLKAB}}$. $\overline{\text{OEAB}}$ is active high. When $\overline{\text{OEAB}}$ is high, the B-port outputs are active. When $\overline{\text{OEAB}}$ is low, the B-port outputs are in the high-impedance state.

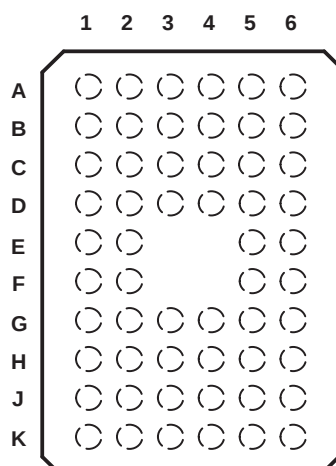
Data flow for B to A is similar to that of A to B, but uses $\overline{\text{OEBA}}$, LEBA , and $\overline{\text{CLKBA}}$. The output enables are complementary ($\overline{\text{OEAB}}$ is active high and $\overline{\text{OEBA}}$ is active low).

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQL OR ZQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
A	A1	LEAB	OEAB	GND	$\overline{\text{CLKAB}}$	B1
B	A3	A2	GND	GND	B2	B3
C	A5	A4	V_{CC}	V_{CC}	B4	B5
D	A7	A6	GND	GND	B6	B7
E	A9	A8			B8	B9
F	A10	A11			B11	B10
G	A12	A13	GND	GND	B13	B12
H	A14	A15	V_{CC}	V_{CC}	B15	B14
J	A16	A17	GND	GND	B17	B16
K	A18	$\overline{\text{OEBA}}$	LEBA	GND	$\overline{\text{CLKBA}}$	B18

SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

INPUTS				OUTPUT B
OEAB	LEAB	$\overline{\text{CLKAB}}$	A	
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↓	L	L
H	L	↓	H	H
H	L	H	X	B ₀ [‡]
H	L	L	X	B ₀ [§]

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

Pin numbers shown are for the DGG, DL, and WD packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O : SN54LVTH16500	96 mA
SN74LVTH16500	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVTH16500	48 mA
SN74LVTH16500	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	64°C/W
DL package	56°C/W
GQL/ZQL package	42°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LVTH16500		SN74LVTH16500		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage			5.5		5.5	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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3.3-V ABT 18-BIT UNIVERSAL BUS TRANSCEIVERS

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SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH16500			SN74LVTH16500			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}		V _{CC} = 2.7 V, I _I = -18 mA		-1.2			-1.2			V
V _{OH}		V _{CC} = 2.7 V to 3.6 V, I _{OH} = -100 μA		V _{CC} -0.2			V _{CC} -0.2			V
		V _{CC} = 2.7 V, I _{OH} = -8 mA		2.4			2.4			
		V _{CC} = 3 V		I _{OH} = -24 mA						
				I _{OH} = -32 mA			2			
V _{OL}		V _{CC} = 2.7 V		I _{OL} = 100 μA			0.2			V
				I _{OL} = 24 mA			0.5			
		V _{CC} = 3 V		I _{OL} = 16 mA			0.4			
				I _{OL} = 32 mA			0.5			
				I _{OL} = 48 mA			0.55			
				I _{OL} = 64 mA			0.55			
I _I	Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND		±1			±1			μA
		V _{CC} = 0 or 3.6 V, V _I = 5.5 V		10			10			
	A or B ports‡	V _{CC} = 3.6 V		V _I = 5.5 V			20			
				V _I = V _{CC}			1			
				V _I = 0			-5			
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					±100			μA
I _{I(hold)}	A or B ports	V _{CC} = 3 V		V _I = 0.8 V			75			μA
				V _I = 2 V			-75			
		V _{CC} = 3.6 V§, V _I = 0 to 3.6 V					±500			
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE/OE = don't care		±100*			±100			μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE/OE = don't care		±100*			±100			μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND		Outputs high			0.19			mA
				Outputs low			5			
				Outputs disabled			0.19			
ΔI _{CC} ¶		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND		0.2			0.2			mA
C _i		V _I = 3 V or 0		4			4			pF
C _{io}		V _O = 3 V or 0		10			10			pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Unused pins at $V_{CC}\text{ or GND}$

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than $V_{CC}\text{ or GND}$.

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WITH 3-STATE OUTPUTS

SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				SN54LVTH16500				SN74LVTH16500				UNIT
				$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			150		150		150		150		MHz
t_w	Pulse duration	LE high		3.3		3.3		3.3		3.3		ns
		CLK high or low		3.3		3.3		3.3		3.3		
t_{su}	Setup time	A before $\overline{\text{CLKAB}}\downarrow$		3.1		3.1		2.9		2.9		ns
		B before $\overline{\text{CLKBA}}\downarrow$		3.1		3.1		2.9		2.9		
		A or B before $\text{LE}\downarrow$	$\overline{\text{CLK}}$ high	1.5		0.6		1.4		0.5		
			$\overline{\text{CLK}}$ low	3.1		2.5		2.9		2.3		
t_h	Hold time	A or B after $\overline{\text{CLK}}\downarrow$		0.4		0.4		0.4		0.4		ns
		A or B after $\text{LE}\downarrow$		1.7		1.7		1.6		1.6		

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

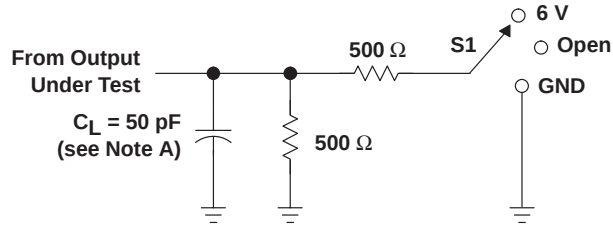
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16500				SN74LVTH16500				UNIT	
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN		MAX
f _{max}			150		150		150			150		MHz
t _{PLH}	B or A	A or B	1.2	3.9	4.1		1.3	2.8	3.7	4		ns
t _{PHL}			1.2	3.9	4.1		1.3	2.6	3.7	4		
t _{PLH}	LEBA or LEAB	A or B	1.4	5.5	5.9		1.5	3.8	5.1	5.7		ns
t _{PHL}			1.4	5.5	5.9		1.5	3.8	5.1	5.7		
t _{PLH}	$\overline{\text{CLKBA}}$ or $\overline{\text{CLKAB}}$	A or B	1.2	5.3	6.1		1.3	3.6	5	5.9		ns
t _{PHL}			1.2	5.3	6.1		1.3	3.5	5	5.9		
t _{PZH}	$\overline{\text{OEBA}}$ or $\overline{\text{OEAB}}$	A or B	1.2	5.1	5.8		1.3	3.6	4.8	5.5		ns
t _{PZL}			1.2	5.1	5.8		1.3	3.6	4.8	5.5		
t _{PHZ}	$\overline{\text{OEBA}}$ or $\overline{\text{OEAB}}$	A or B	1.6	6.1	6.6		1.7	4.5	5.8	6.3		ns
t _{PLZ}			1.6	6.1	6.6		1.7	4.1	5.8	6.3		

[†] All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

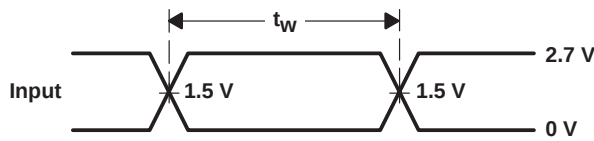
SN54LVTH16500, SN74LVTH16500 3.3-V ABT 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS701F – JULY 1997 – REVISED SEPTEMBER 2003

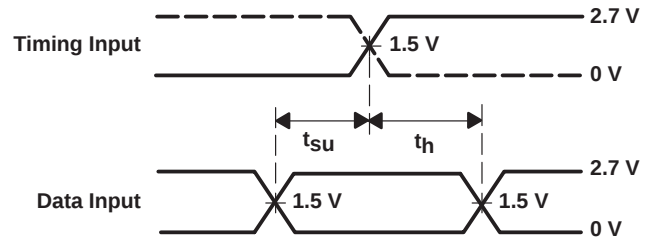
PARAMETER MEASUREMENT INFORMATION



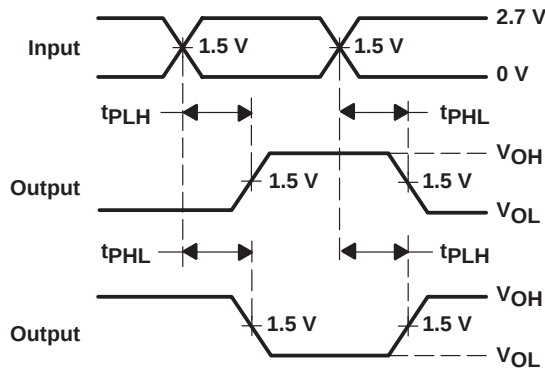
LOAD CIRCUIT



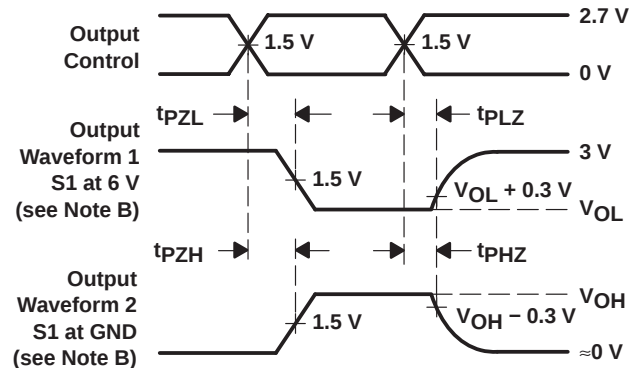
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74LVTH16500DGGRG4.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500
SN74LVTH16500DGGR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500
SN74LVTH16500DGGR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500
SN74LVTH16500DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500
SN74LVTH16500DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16500DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16500DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

TUBE

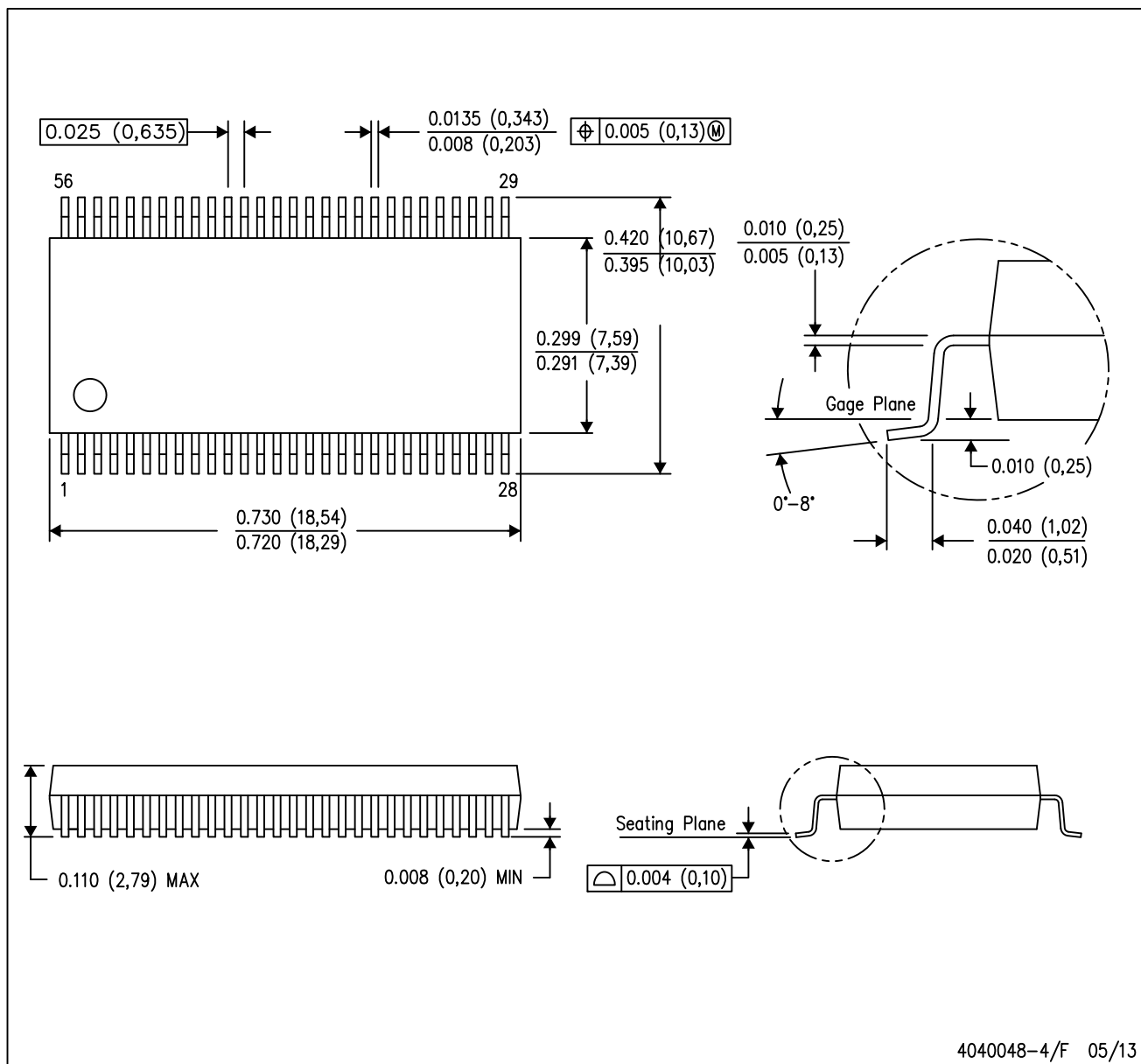


*All dimensions are nominal

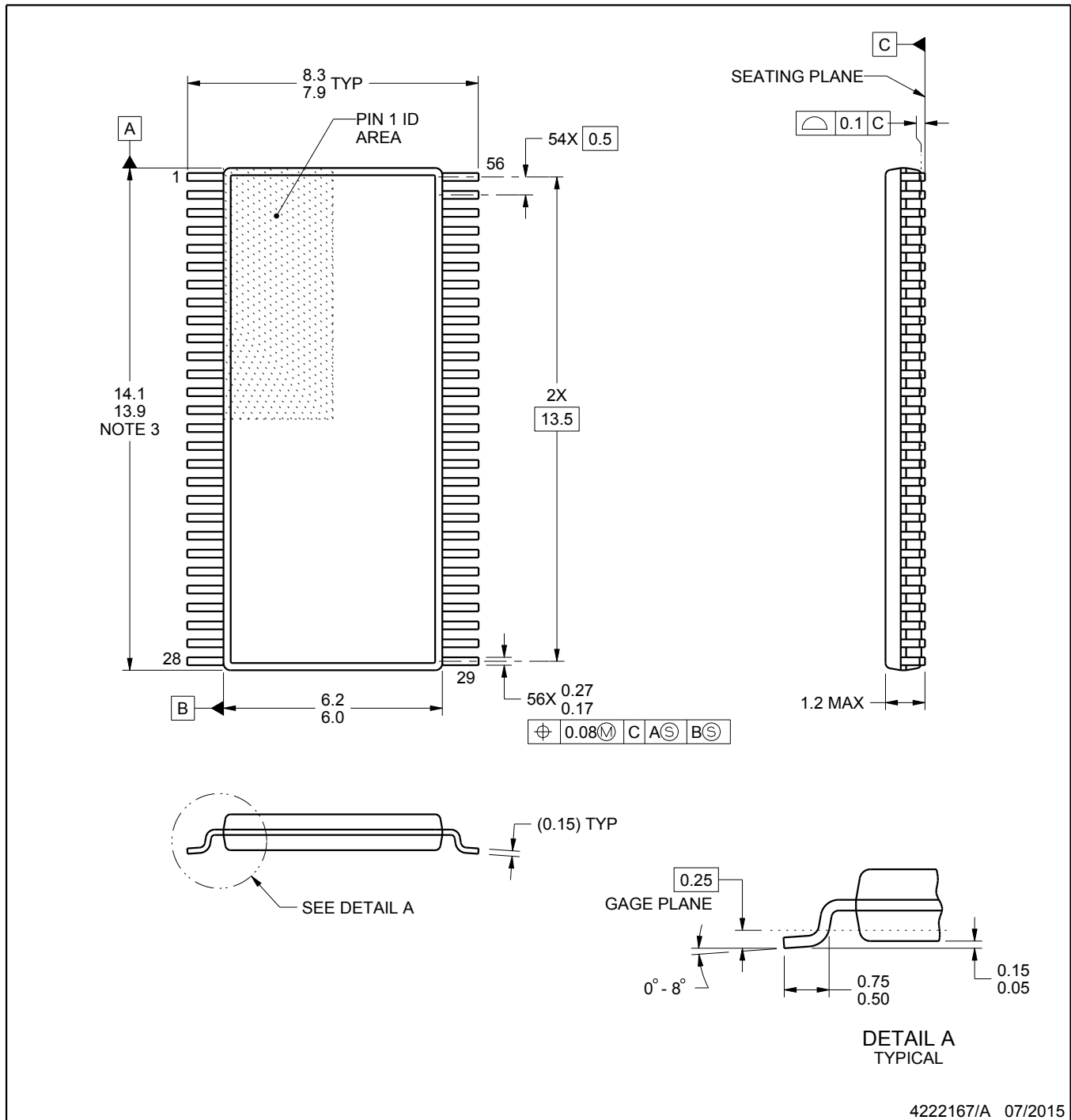
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVTH16500DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74LVTH16500DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118



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NOTES:

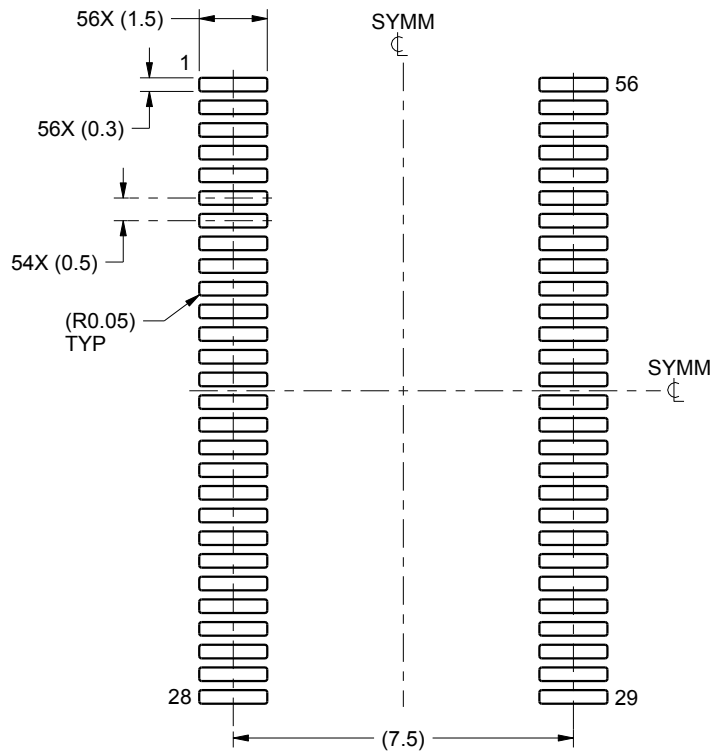
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

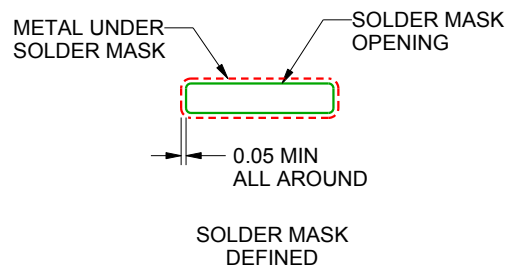
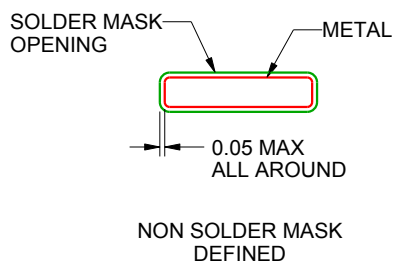
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

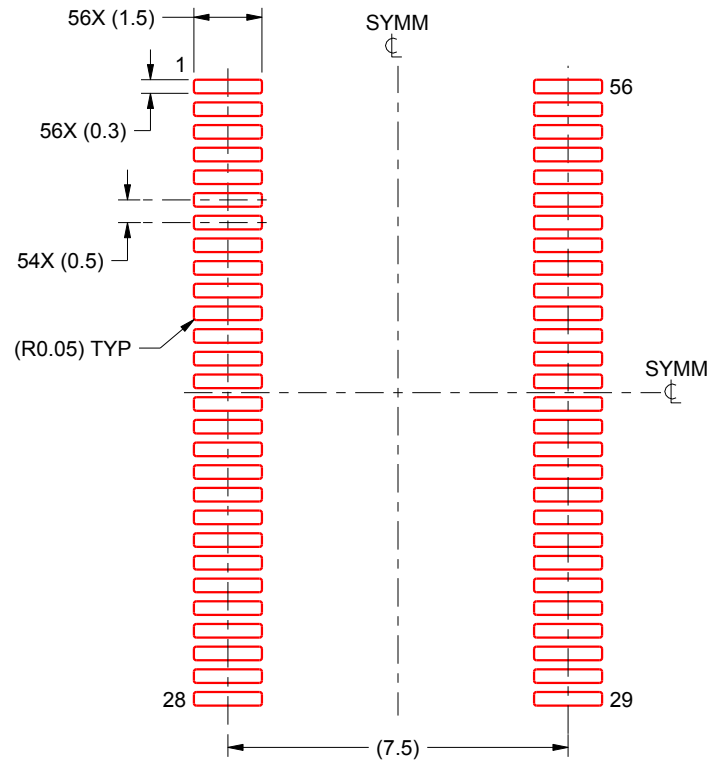
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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